

DS1xxDF1610 APPLICATIONS BOARD

1. High speed traces should be tightly coupled for 100 ohms diff impedance
2. When traces break to connectors, the impedance should be 50 ohm single ended
3. Thermal keep out area should have no markings on board, $r1 = 12\text{mm}$, $r = 37\text{mm}$
4. All headers and connectors should have all pins labeled in the top silk
5. OK to put MSP and power circuitry on the bottom of the pcb
6. There should be at least 4 locations for mechanical standoffs, more may be necessary depending on the final board dimensions
7. AC coupling caps on the TX nets should have GND cut outs





